

### ■ Features

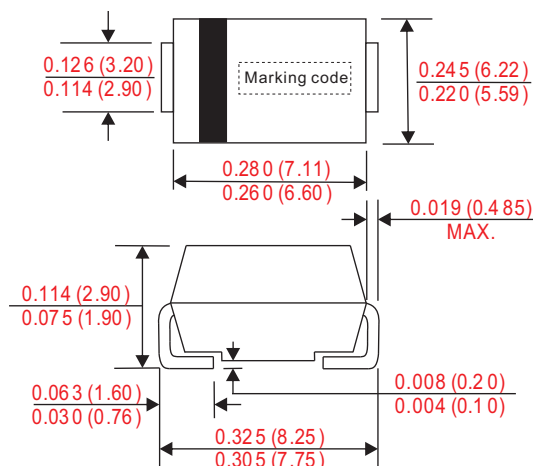
- Electrostatic discharge (ESD) test under IEC6100-4-2 standard >16KV(SKS22C~SKS26C).
- Low profile surface mounted application in order to optimize board space.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Suffix "G" indicates Halogen-free part, ex. SKS22CG.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

### ■ Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AB / SMC
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : 0.007 ounce, 0.226 gram

### ■ Outline

SMC(DO-214AB)



Dimensions in inches and (millimeters)

### ■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	$I_O$			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	$I_{FSM}$			50	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	$I_R$			0.5	mA
	$V_R = V_{RRM} \quad T_A = 100^\circ\text{C}$				20	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		30		pF
Thermal resistance	Junction to ambient	$R_{\theta JA}$		50		°C/W
Storage temperature		$T_{STG}$	-55		+175	°C

Symbol	Marking code	Max. repetitive peak reverse voltage $V_{RRM}$ (V)	Max. RMS voltage $V_{RMS}$ (V)	Max. DC blocking voltage $V_R$ (V)	Max. forward voltage @2A, $T_A = 25^\circ\text{C}$ $V_F$ (V)	Operating temperature $T_J$ (°C)
SKS22C	KS22	20	14	20	0.35	-50 ~ +150
SKS24C	KS24	40	28	40	0.40	
SKS26C	KS26	60	42	60	0.50	

### ■ Rating and characteristic curves

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

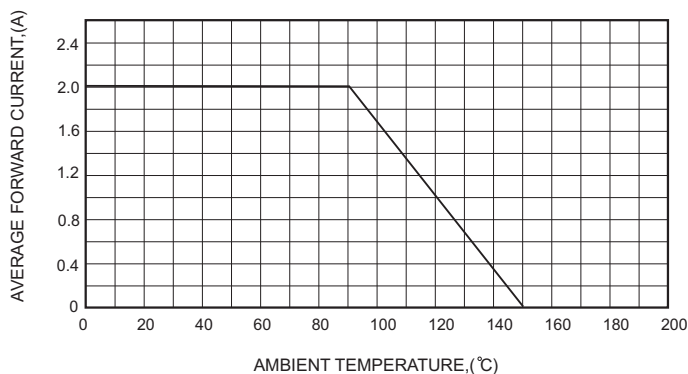


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

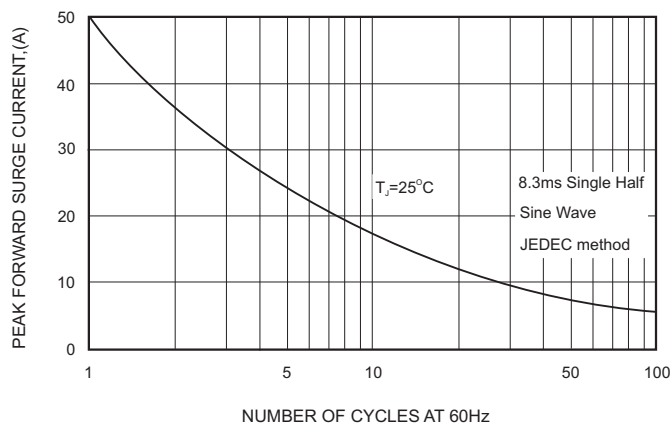


FIG.4-TYPICAL JUNCTION CAPACITANCE

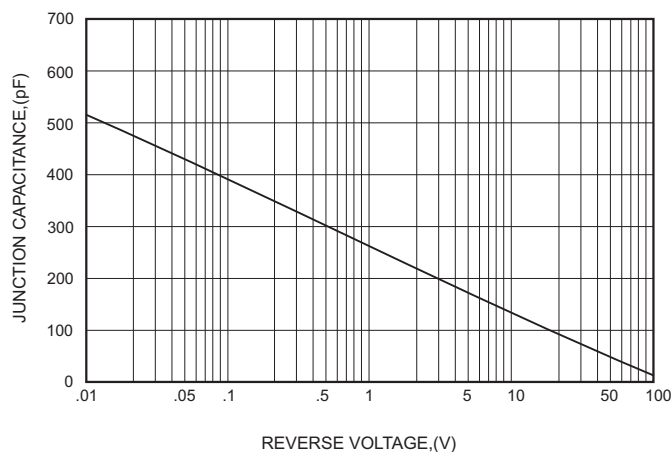


FIG.2-TYPICAL FORWARD CHARACTERISTICS

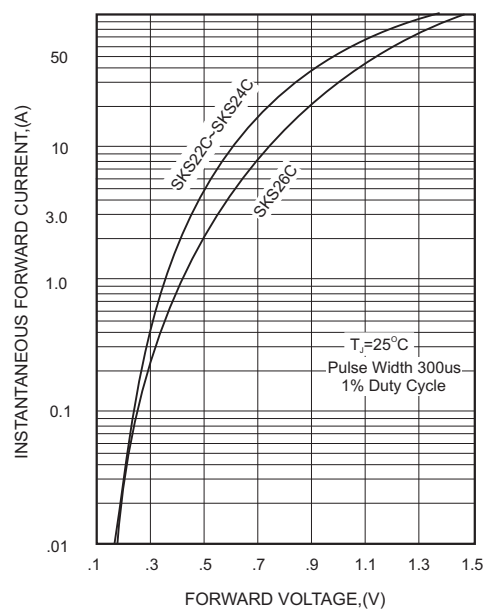
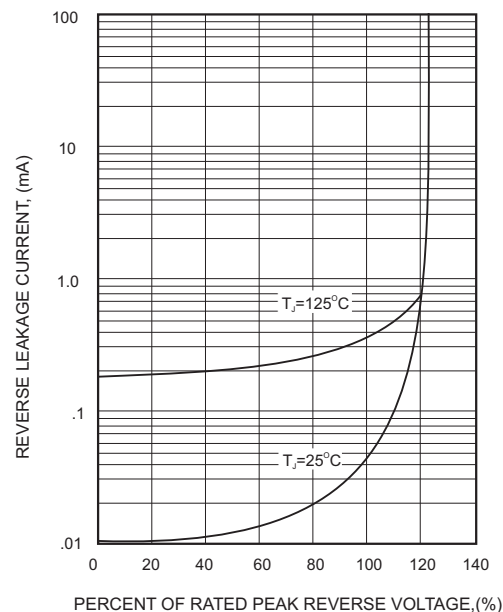
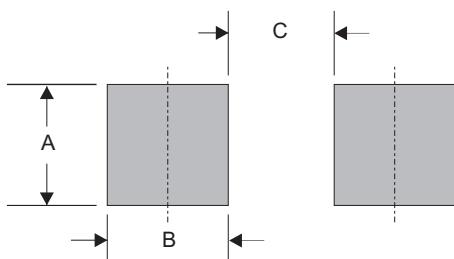


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



### ■ SMC foot print



A	B	C
0.132 (3.30)	0.098 (2.50)	0.176 (4.40)

Dimensions in inches and (millimeters)

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